



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

**Notification# 20191003002
Datasheet for SN74AUP1G32
Information Only**

Date: May 18, 2020

Dear Customer:

This is an information-only announcement of a change to the datasheet for a device that is currently offered by Texas Instruments.

The changes discussed within this notification are for your information only.

Any negotiated alternative change requirements will be provided via the customer's defined process. Customers with previously negotiated, special requirements will be handled separately. Any inquiries should be directed to your local Field Sales Representative.

For questions regarding this notice, contact your local Field Sales Representative or the PCN team (PCN_admin_team@list.ti.com).

Sincerely,

PCN Team
SC Business Services

**Information Only
Attachments**


Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE
SN74AUP1G32DSF2

CUSTOMER PART NUMBER
36020410

Technical details of this Product Change follow on the next page(s).

PCN Number:	20191003002	PCN Date:	May 18, 2020								
Title:	Datasheet for SN74AUP1G32□										
Customer Contact:	PCN Manager	Dept:	Quality Services								
Change Type:											
<input type="checkbox"/> Assembly Site	<input type="checkbox"/> Design	<input type="checkbox"/> Wafer Bump Site									
<input type="checkbox"/> Assembly Process	<input checked="" type="checkbox"/> Data Sheet	<input type="checkbox"/> Wafer Bump Material									
<input type="checkbox"/> Assembly Materials	<input type="checkbox"/> Part number change	<input type="checkbox"/> Wafer Bump Process									
<input type="checkbox"/> Mechanical Specification	<input type="checkbox"/> Test Site	<input type="checkbox"/> Wafer Fab Site									
<input type="checkbox"/> Packing/Shipping/Labeling	<input type="checkbox"/> Test Process	<input type="checkbox"/> Wafer Fab Materials									
		<input type="checkbox"/> Wafer Fab Process									
Notification Details											
Description of Change:											
<p>Texas Instruments Incorporated is announcing an information only notification. The product datasheet(s) is being updated as summarized below. The following change history provides further details.</p>											
 <div style="text-align: right;"> SN74AUP1G32 <small>SCES580J – JUNE 2004 – REVISED SEPTEMBER 2019</small> </div>											
<table border="1" style="width: 100%;"> <thead> <tr> <th style="text-align: left;">Changes from Revision I (June 2014) to Revision J</th> <th style="text-align: right;">Page</th> </tr> </thead> <tbody> <tr> <td>• Changed format of Pin Configuration images to allow for HTML search function</td> <td style="text-align: right;">3</td> </tr> <tr> <td>• Corrected YFP package pin descriptors in the Pin Functions table</td> <td style="text-align: right;">3</td> </tr> <tr> <td>• Added Thermal Information for the DPW package</td> <td style="text-align: right;">5</td> </tr> </tbody> </table>				Changes from Revision I (June 2014) to Revision J	Page	• Changed format of Pin Configuration images to allow for HTML search function	3	• Corrected YFP package pin descriptors in the Pin Functions table	3	• Added Thermal Information for the DPW package	5
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• Added Thermal Information for the DPW package	5										
The datasheet number will be changing.											
Device Family	Change From:	Change To:									
SN74AUP1G32□	SCES580I	SCES580J									
Reason for Change:											
To accurately reflect device characteristics.											
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):											
No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.											
Changes to product identification resulting from this PCN:											
None.											
Product Affected:											
SN74AUP1G32DBVR	SN74AUP1G32DBVT	SN74AUP1G32DCKR	SN74AUP1G32DCKRE4								
SN74AUP1G32DCKT	SN74AUP1G32DPWR	SN74AUP1G32DRLR	SN74AUP1G32DRY2								
SN74AUP1G32DRYR	SN74AUP1G32DSF2	SN74AUP1G32DSFR	SN74AUP1G32YFPR								
SN74AUP1G32YZPR											

For questions regarding this notice, e-mails can be sent to the contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
WW PCN Team	PCN_ww_admin_team@list.ti.com

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